

#### **TSD**

### **■ FEATURES**

- End stackable for standard 0.1" integrated circuit pitch.
- Molded 0.3" integrated circuit packing outline allowing automatic insertion.
- Smaller size makes better heat convection during PC board reflow wave soldering.
- Top tape sealed to withstand wave soldering, board washing.
- All plastics are UL 94V-0 grade fire retardant.
- Twin contacts designed to ensure stable contact.
- Gold plated contact to ensure low contact resistance and Tin plated terminals to prevent contamination during soldering.
- RoHS Compliant

#### APPLICATIONS

- Numerical setting for computer terminal equipment
- Price setting for vending machines
- Programming for game machines
- Programming for industrial equipment and measuring instruments

#### **■ SPECIFICATIONS**

#### 1.ELECTRICAL

Contact rating	switching	25mA, 24VDC	
	non-switching	100mA	
Contact resistance	initial	50mΩ Max.	
	after life test	100mΩ Max.	
Insulation resistance		1000MΩ Min. at 100VDC	
Dielectric strength		500VDC Min. for 60 seconds	
Capacitance between adjacent switches 5pF Max.			



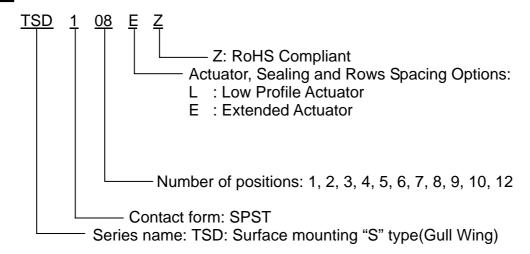


# TSD Series TPND-STACKABLE SMT TYPE

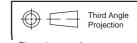
# 2.MECHANICAL and ENVIRONMENTAL

Temperature rating	operating	-25°C to +70°C
	storage	-40°C to +85°C
Operation force		800g Max.
Mechanical life		2000 operations
Humidity		95% RH, 40°C for 96 Hrs.
<ul><li>Vibration</li></ul>		10Hz-55Hz-10Hz for 6 Hrs.
Reflow soldering heat for SMT type (reference only)		Max. 260 °C 240 °C

# **■ PART NUMBERING SYSTEM**

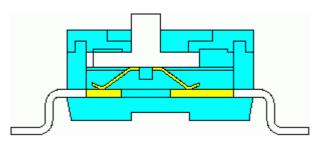






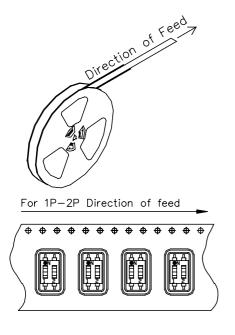
# **■** CONSTRUCTION

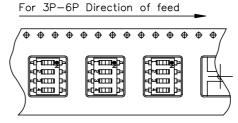
## **TSD**

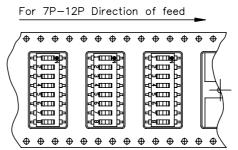


## PACKAGING

1.Tape & Reel Packaging (per EIA STANDARD)







TYPE	No. of pcs per reel
1P	2000
2P	1300
3P	1000
4P	1000
5P	1000
6P	1000
7P	1000
8P	1000
9P	1000
10P	1000
12P	1000

(ESL series: 1 pole switch is unavailable)





Dimensions are shown: mm Specifications and dimensions subject to change

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## **DIMENSIONS AND CIRCUITRY**

